



**Specialty Epoxy building blocks for demanding coating, adhesive applications.**

Presenter:

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CVC Thermoset Specialties, Inc.,

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## Epoxy Resins:

First commercially developed in 1936

- ❖ Dr. Pierre Castan - Switzerland
- ❖ Dr. S.O Greenlee - USA

First Commercial producer:

- ❖ Ciba Giegy - Switzerland
- ❖ Devoe-Reynolds – USA

First Epoxy resin synthesis:

- ❖ Reaction product of Bisphenol- A and Epichlorohydrin

## **Current Scenario:**

- ❖ Epoxy resin produce in multi 100K lbs world wide
- ❖ More than 20 large commercial producers worldwide.
- ❖ Epoxy resin produce by using different starting material other than Bisphenol-A

**Bisphenol-A epoxy resin is still workhorse of the industry.**

## **Bisphenol-A epoxy resin offers:**

( When cured with appropriate curing agents)

- ❖ Adhesion
- ❖ Chemical resistance
- ❖ Mechanical properties
- ❖ Thermal properties.

## **Applications:**

Currently epoxy resin used in many diverse applications:

- ❖ Civil engineering
- ❖ Pultrusion and composites
- ❖ Adhesives
- ❖ Coatings

## **With technological advancement:**

Various application demands higher performance from epoxy resins

- ❖ Better Chemical resistance
- ❖ Better UV resistance
- ❖ Faster cure at wide range of temperature  
( especially at low temperature)
- ❖ Better toughness  
( especially at lower temperature)

CVC has unique products that helps to meet these high performance requirements.



**Better Chemical resistance**

## Example: 98 % Sulfuric acid immersion

Samples after 24 hrs immersion in 98 % sulfuric acid.



HC = **Standard LER** with heat cured curing agent

RTC = **Standard LER** with room temperature curing agent

## Structure comparison

Epoxy resin	Chemical resistance	Functionality	Viscosity	Comment
Bisphenol-A	Good	2	11000-14000 cP at 25C	Good crosslink density
Bisphenol-F	Better	2.05	3000 – 6000 cP at 25C	Small molecule, better crosslink density
Novolacs	Best	2.3 – 3.8	up to 40000 cP at 52C	Much higher crosslink density. Higher viscosity

### Ideal solution:

- ❖ Very high chemical resistance
- ❖ Low in viscosity at 25C
- ❖ Can be used as diluent for EPN's for better handling



# Acid resistance

Starting formulation: 7 days at 25C

Resin system	Composition., %	Viscosity @ 25C, cP
Epalloy 8230	100	3800
Epally 8250	100	18000
Epalloy 8230/Erisys GE 30	80/20	1400
Epalloy 8230/RDGE	70/30	1500
Epalloy 8250 / RDGE	75/25	5500

Epalloy 8230, 8230  
(Epoxy Phenol Novolacs, F = 2.3 & 2.5)  
Erisys GE 30  
(Trimethylpropane triglycidyl ether  
Erisys RDGE  
( Resorcinol Diglycidyl ether)

Curing agent	Supplier	Composition
624CE	Henkel	Aliphatic amine adduct
670CE	Henkel	IPD/BA blend
676CE	Henkel	DCH/NP blend
PAC 1693	Air Products	DCH/BA blend
PAC 2280	Air Products	Polycyclic aliphatic amine / BA blend
HY 265	Ciba	Cycloaliphatic amine/ BA blend

IPD = Isophorone Diamine  
BA = Benzyl Alcohol  
NP = Nonyl Phenol

# 28 Days immersion in 98% Sulphuric acid

(Curing : 7 days at RTC)

Resin system	Composition, %	Curing agent					
		624CE	670CE	676CE	PAC 1693	PAC 2280	HY 265
Epalloy 8230	100	-0.9	-0.9	-24.0	0.5	0.4	-11.9
Epalloy 8250	100	0.4	-0.7	-15.8	-0.1	-0.1	-3.0
Epalloy 8230/Erisys GE 30	80/20	-1.0	-7.1	-50.7	-0.4	0.6	-22.8
Epalloy 8230/RDGE	70/30	-0.3	0.5	-9.5	0.5	0.4	1.0
Epalloy 8250 / RDGE	75/25	0.3	-0.2	-7.4	0.3	0.3	-0.0



After 24 hrs in 98 % sulfuric acid

After 28 days in 98 % sulfuric acid

## 28 Days immersion in Glacial Acetic Acid

(Curing : 7 days at RTC)

Resin system	Composition, %	Curing agent					
		624CE	670CE	676CE	PAC 1693	PAC 2280	HY 265
Epalloy 8230	100	D	D	D	-12.7	9.2	D
Epalloy 8250	100	D	D	D	-7.7	15.2	D
Epalloy 8230/Erisys GE 30	80/20	6.0	D	D	D	3.3	D
Epalloy 8230/RDGE	70/30	-2.6	-3.9	D	-3.8	17.7	D
Epalloy 8250 / RDGE	75/25	4.9	-7.6	D	-1.5	10.5	D

\*D= Destroy

# Acid resistance- Heat cured

Curing: Gel at RT + 2hrs at 80C + 3 hrs at 150C

Resin system	Composition., %	Viscosity @ 25C, cP
Epalloy 8230	100	3800
Epally 8250	100	18000
Epalloy 8230/Erisys GE 30	80/20	1400
Epalloy 8230/RDGE	70/30	1500
Epalloy 8250 / RDGE	75/25	5500

Epalloy 8230, 8230  
(Epoxy Phenol Novolacs, F = 2.3 & 2.5)  
Erisys GE 30  
(Trimethylpropane triglycidyl ether  
Erisys RDGE  
( Resorcinol Diglycidyl ether)

Curing agent	Composition
PACM	Polycyclic aliphatic amine
IPD	Isophorone Diamine
DCH	1,2-Diamino cyclohexane

## 28 Days immersion in 98% Sulphuric acid

Curing: Gel at RT + 2hrs at 80C + 3 hrs at 150C

Resin system	Composition, %	Curing agent		
		PACM	IPD	DCH
Bis- A	100	D	D	D
Epalloy 8230	100	1.0	1.0	1.0
Epalloy 8230/RDGE	70/30	1.0	1.0	1.3

## 28 Days immersion in Glacial Acetic Acid

Curing: Gel at RT + 2hrs at 80C + 3 hrs at 150C

Resin system	Composition, %	Curing agent		
		PACM	IPD	DCH
Bis- A	100	5.0	6.1	7.3
Epalloy 8230	100	7.5	9.5	6.2
Epalloy 8230/RDGE	70/30	5.5	6.2	4.3

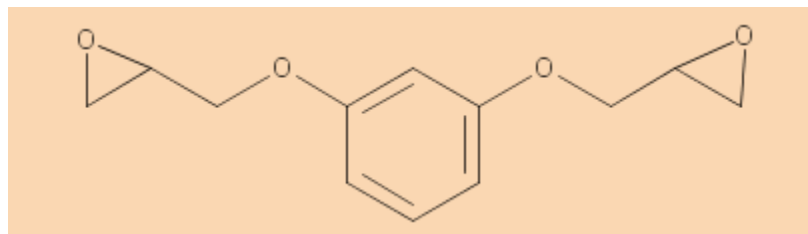
## Remarks:

- ❖ Epoxy Phenol Novolacs are giving better acid resistance than Bisphenol-A epoxy
- ❖ Resorcinol Diglycidyl ether and Epoxy Phenol Novolacs blend give improved acid resistance than Epoxy Phenol Novolacs alone.

# Erisys RDGE

## Resorcinol Diglycidyl ether

Structure



Property	EEW g/eq	Viscosity @ 25C cP	Functionality
LER- BPA based	180-190	10000 – 14000	2
BPF resin	165 – 180	3000 – 6000	2.05
EPN's	170 – 190	18000 - semisolid	2.3 -3.9
RDGE	118 – 125	300 – 500	2
RDGE modified EPN's	152 -160	5000 - 9000	2.4 -2.8





**Better UV Stability**

## Structure comparison

Structure	Chemical nature	UV stability	Viscosity	Comment
Bisphenol-A	Aromatic	Poor	11000-14000 cP at 25C	Improve by using cycloaliphatic hardener
Bisphenol-F	Aromatic	Poor	3000 – 6000 cP at 25C	Improve by using cycloaliphatic hardener
Novolacs	Aromatic	Poor	up to 40000 cP at 52C	Need solvent to reduce viscosity.

Ideal solution:

- ❖ 100 % cycloaliphatic resin
- ❖ Very low in viscosity at 25C

# Formulation components

## Resin component

Sample	Composition	Description
R1	Epon 828/TMPTA/TPGDA ( 80/10/10)	Bis-A epoxy+fast acrylate+flexible acrylate
R2	Epalloy 5001/TMPTA (90/10)	Hydrogenated epoxy + fast acrylate
R3	R1/R2 ( 50/50)	
R4	Epon 828/Ancarez 2364/Epodil 748 (24/50/16)	Urethane modified Bis A epoxy
R5	R2/R4 (50/50)	

## Hardener component

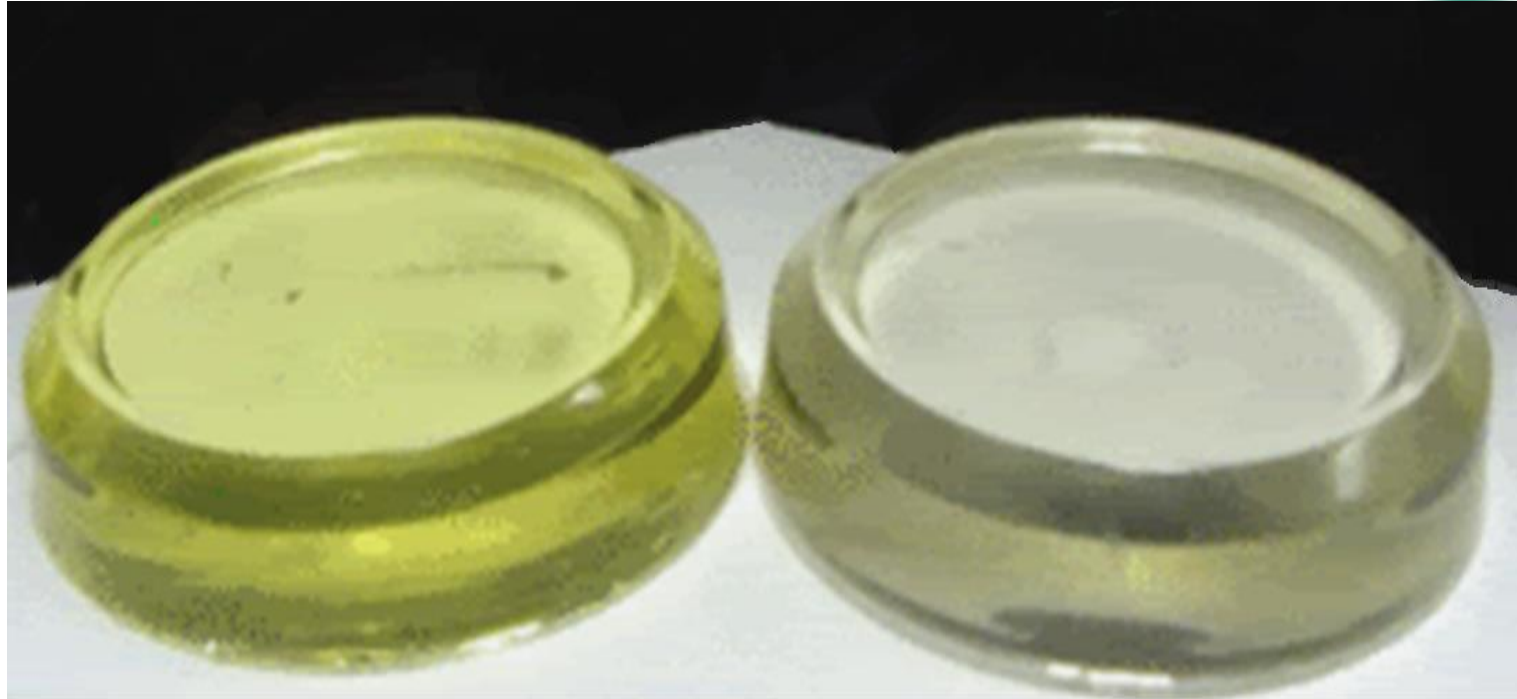
Sample	Composition	Description
A1	PACM	Good gloss and color retention
A2	Cycloaliphatic amine + polyether amine	High reactivity and flexibility than A1
A3	Isolated Aliphatic amine adduct	Fast reactivity, good gloss retention
A4	Aliphatic amine + cycloaliphatic amine + high MW polyether amine	Slow cure, high flexibility

# Gloss Retention and Yellowing Resistance

Sample	Gloss 0 time 20o/60o	Gloss 7 days UV 20o/60o/85o	Yellowness 0 time	Yellowness 3 day UV	Yellowness 7 Day UV
R1A1	90/96	55/78/86	1.0	27.0	49.7
R1A2	39/67	4/20/48	3.2	57.0	62.7
R1A3	75/97	28/60/62	2.8	56.7	66.0
R2A1	91/97	76/89/91	2.5	12.8	22.5
R2A2	28/76	13/60/78	8.1	26.0	46.5
R2A3	85/95	12/28/28	4.7	49.2	61.9
R3A1	5/22	1/6/21	13.8	26.4	29.1
R3A2	73/100	2/11/57	7.8	51.1	61.5
R3A3	97/95	13/22/13	3.5	48.9	59.3
R4A2	22/38	1/3/13	20.8	37.5	60.8
R5A2	57/76	7/20/62	11.9	56.7	68.9

- ❖ System R2A1 is clearly the most promising candidate for a durable weatherable coating.
- ❖ It exhibited good reactivity, hardness, toughness and weathering

## UV resistance



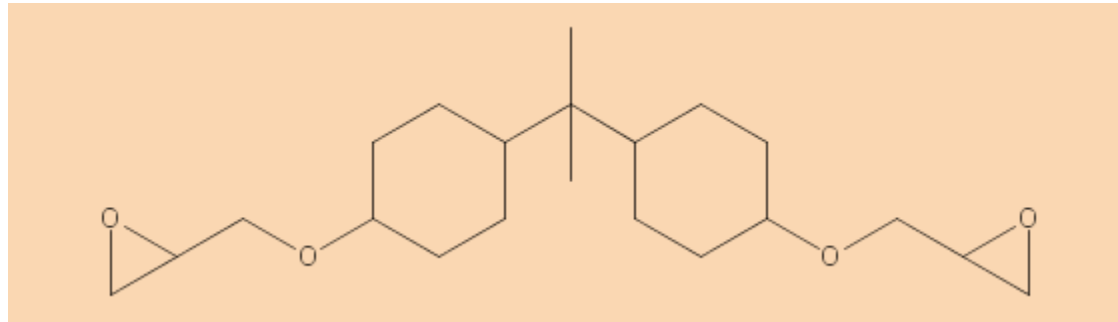
Bisphenol-A epoxy resin  
exposed to  
Sunlight for 10 days

Epalloy 5001 epoxy resin  
exposed to  
Sunlight for 10 days

# Epalloy 5000/5001

## Hydrogenated Bisphenol-A Diglycidyl ether

Structure



Property	EEW g/eq	Viscosity @ 25C, cP	Functionality
Epalloy 5000	210-230	1500-2500	2
Epalloy 5001	190-210	2000 – 4500	2.4

- Faster cure at wide temperature**  
**Especially at low or subzero temperature**

## Structure comparison

Structure of resin	Curing agent	Comment
Bisphenol-A	Polyamide	Good reactivity at RT Very long gel time at 5C or below
	Aliphatic amine	Faster reactivity, brittle, amine blush
	Cycloaliphatic amine	Slower reactivity at RT.
	Mercaptan	faster reactivity at 5C or below. Smell and handling problem.
	Phenalkamine	Good reactivity at 5C Color issue
Bisphenol-A + acrylates	Amine	Faster reactivity at 5C or below Smell, handling issue . Loss in property.
Bisphenol-A + Benzyl alcohol	Amine	Faster reactivity at 5C or below Smell, handling issue . High VOC. Loss in property.
Bisphenol-A + Nonyl phenol	Amine	Faster reactivity at 5C or below Smell, handling issue . Loss in property.

Ideal solution:

- ❖ Resin with higher reactivity ability with any curing agent.



# Mercaptan replacement

Formulation	A	B
DER 331 ( Standard Bisphenol-A epoxy resin)	100	0
Epalloy 7200 (Modified Bisphenol-A epoxy resin)	0	85
Erisys GE 20 ( Neopentyl diglycidyl ether)	0	15
Capcure 3-800 (polymercaptan)	90	0
Versamine EH-50	10	0
Versamine F-11	0	49

Property	A	B
Gel time ( 20 gm), min	3.10	4.20
D Hardness @ 15 min	55/42	79
D Hardness @ 30 min	73	82
D Hardness @ 40 min	74	84
D Hardness @ 16 hrs	78	82
Water absorption ( 24 hrs boil), %	10	7.97

## Advantage:

- ❖ No odor
- ❖ Longer working time
- ❖ Faster property development
- ❖ Improved water absorption

# Acrylate replacement

Formulation	A	B
DER 331 ( Standard Bisphenol-A epoxy resin)	75	0
Epalloy 7200 (Modified Bisphenol-A epoxy resin)	0	80
Epon 8111 ( Acrylated resin)	25	0
Erisys GE 20 ( Neopentyl diglycidyl ether)	0	20
TETA (Tri ethylene tetra amine)	14	13.4

# Acrylate replacement

Property	A	B*
Viscosity @ 25C, cP	5300	5200
Gel time ( 20 gm), min	12	11
Hardness ( hours to D=80+)	7	1
Tg ( 48 hrs RTC), oC	51	70
Tg ( 10 days RTC), oC	53	80
MEK Rub/Heat cure1	>300	>300
MEK Rub/16 Hrs. RTC	< 50(2)	>300
MEK Rubs/4 days RTC	>300(2)	>300
Xylene Resistance/Heat cure (1)	-0.004%(3)	+0.056%(3)
Xylene resistance/4 days RTC	+1.05%(3)	+0.17%(3)

(1)= 16 Hrs at RTC + 2 Hrs at 100C

(2) = Stained film appearance

(3) = 3 days immersion

**B\*** = Formulation with Epalloy 7200

## Advantage:

- ❖ No odor
- ❖ Similar working time
- ❖ Faster property development
- ❖ Higher chemical resistance

## Low temperature faster cure

With polyamide and Phenalkamine K 541 as Hardener

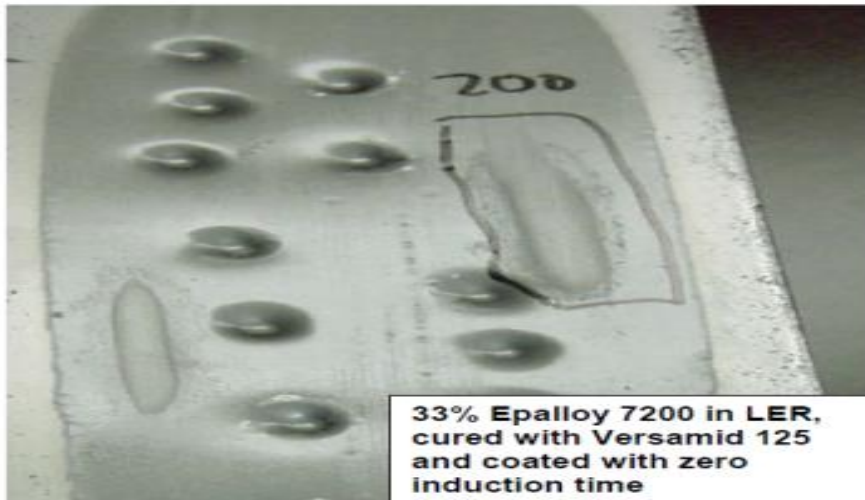
Formulation	DER 331x90	Epalloy 7200x90	DER 331x90	Epalloy 7200x90
Hardener	Versamide 125		Phenalkamine K-541	
Resin Viscosity @ 25C, cP	725	4170	725	4170
Resin solid	90	90	90	90
VOC ( gm/liter)	72	74	68	68
Dry time ( Hrs), RTC	19	4	16	15
Dry time ( Hrs) , 4oC	88	42	48	19
MEK Double Rubs, RTC	Very poor	300 slight dull	Fail	300 dull
MEK Double Rubs, 4oC	Very poor	300 dull	Fail	300 dull
Gardner impact ( inch- lbs), RTC	12	10	13.5	6
Gardner impact ( inch- lbs), 4oC	X	7	X	6

## Low temperature faster cure

With polyamide and Phenalkamine K 541 as Hardener

Epalloy 7200 containing formulation is showing ...

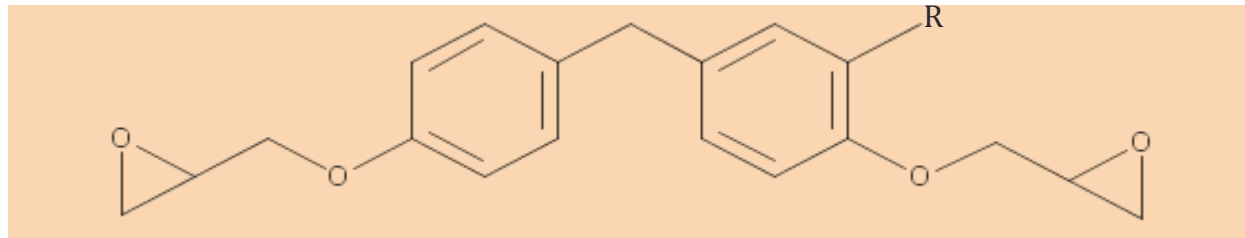
- ❖ faster property development
- ❖ better chemical resistance
- ❖ better impact resistance



# Epalloy 7200

## Modified Bisphenol-A diglycidyl ether

Structure

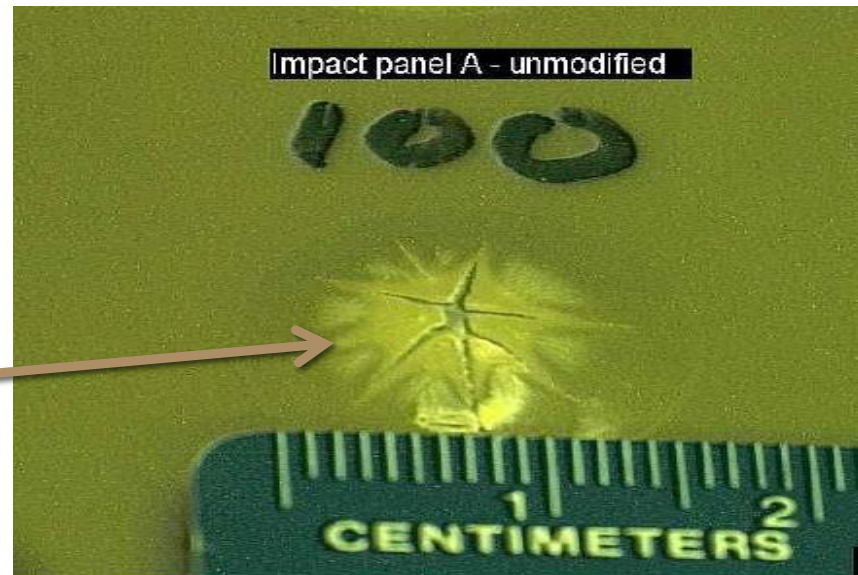


Resin	EEW g/eq	Viscosity @ 25C, cP	Functionality
Standard Bisphenol A epoxy resin	180-190	11000 – 14000	2
Epalloy 7200	195-215	2000 – 4000 @ 72C	2

- Better Toughness at Wide temperature  
Especially at low or subzero temperature**

- ❖ Epoxy in general are brittle when cured.
- ❖ Brittleness is increasing when temperature is low.

Impact – Brittle-Crack



Ideal solution:

- ❖ Resin with modifier which improves impact strength or toughness.



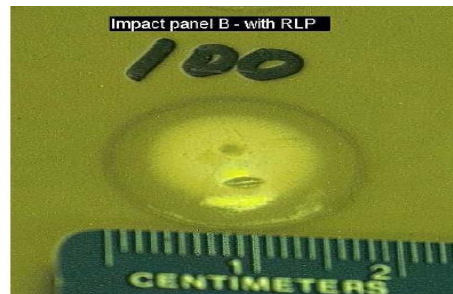
# Toughened powder coating

## Model formulation

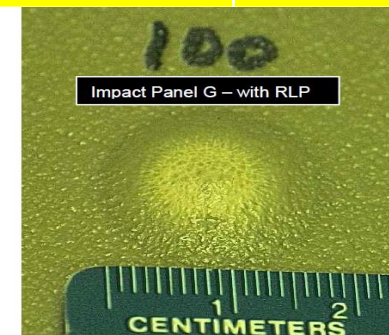
Formulation	A	B	C
Epon 2004 (Solid epoxy resin)	100	0	0
Hypox RA 840	0	100	0
Hypox RA 1340	0	0	100
Epikure P-104 (Phenolic curing agent)	4	3.5	3.5
Barium sulfate	35	35	35
Modaflow	1.4	1.4	1.4
Coating property			
Impact , in-lbs (Direct/ reverse)	40/40	160/160	160/160



Formula A – Unmodified Epon 2004



Formula B – 1300X8 CTBN Modified Epon 2004



Formula G – 1300X13 CTBN Modified Epon 2004

# Toughened Epoxy Adhesives

High peel strength 2 part adhesive ( Heat Cured)

Formulation	1	2	3
Standard Bisphenol-A epoxy	100	62.5	62.5
Hypox RA 840	0	62.5	0
Hypox RA 1340	0	0	62.5
Aliphatic amine adduct	28.2	27.4	27.4
Polyamide	26.3	25.6	25.6
Filler ( Tabular Alumina)	40	40	40
Rubber concentration, phr	0	25	25
Property( cured 1hr at 125C) Subtract -Cold roll steel			
Lap Shear , Mpa (Psi)	4.8 (700)	11.3 (1640)	13.1 (1900)
T-peel, Kg/cm(Pli)	0.9 (4.9)	2.9 (16.4)	6.0 ( 33.3)
Subtract – Electrogalvanized steel			
Lap Shear , Mpa (Psi)	3.5 (505)	11.4 (1660)	8.1 ( 1180)
T-peel, Kg/cm(Pli)	0.8 ( 4.3)	3.3 (18.2)	4.3 (24.3)

# Toughened epoxy adhesives

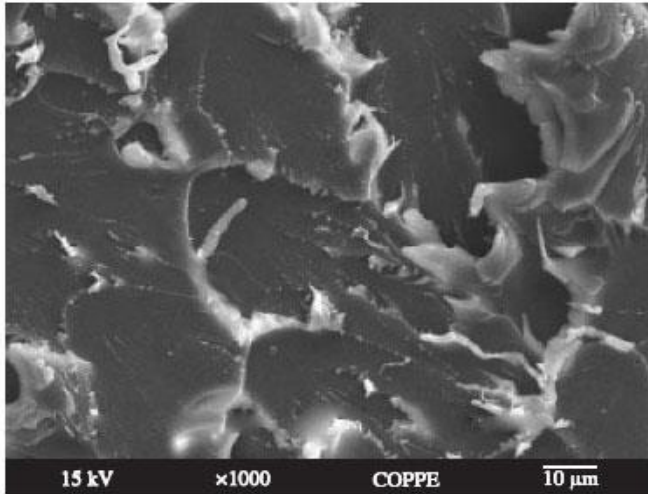
High peel strength 2 part adhesive ( RT Cured)

Formulation	1	2	3
Standard Bisphenol-A epoxy	100	77.5	77.5
Hypox RA 840	0	37.5	0
Hypox RA 1340	0	0	37.5
Aliphatic amine adduct	60	59.3	59.3
Atomite Whiting	30	30	30
Rubber concentration, phr	0	25	25
Property( cured 2 weeks at RT) Subtract –sand blasted Cold roll steel			
Lap Shear , Psi at -40C	1000	3500	1500
Lap Shear , Psi at RT	1200	2700	2500
Lap Shear , Psi at 83C	< 100	< 100	< 100
T-peel, Pli at RT	< 5	28	12

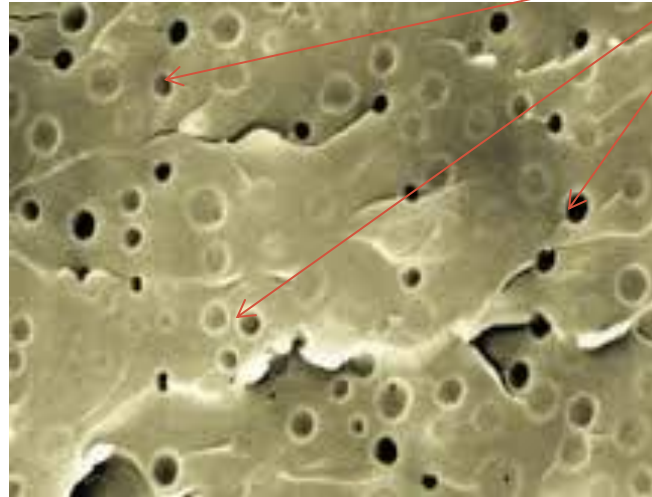
## Toughening:

CTBN/ATBN modified epoxy formulations are better .

- in fracture toughness
- in T-peel strength – especially at RT and low temperature
- in Lap shear strength ( adhesiveness).



(b)



Micro phase separated  
Polymer.  
Energy diffuser.  
Stop crack propagation

Epoxy without toughened- brittle    Epoxy with Hypox- Toughened

## Conclusion:

Utilizing these specialty building blocks, formulator can...

- ❖ Increase chemical resistance of coating
- ❖ Increase UV stability of coating
- ❖ Increase work output even at lower temperature coating, adhesives, composite
- ❖ Find better alternate to Mercaptan and / or acrylates in coating , adhesives
- ❖ Improve fracture toughness of brittle epoxy coating , adhesive, composite even at -40C